

**Process for fabricating a donor substrate for the transfer of a piezoelectric layer
to a carrier substrate**

ABSTRACT

The invention relates to a process for fabricating a donor substrate (1) for transferring a piezoelectric layer to a carrier substrate, comprising the following successive steps:

- (a) providing a piezoelectric substrate (5) and a handle substrate (2),
- (b) depositing a photopolymerizable adhesive layer (6) on a main face of the handle substrate (2) or of the piezoelectric substrate (5),
- (c) bonding the piezoelectric substrate (5) with the handle substrate (2) via the adhesive layer (6) to form a heterostructure (7),
- (d) irradiating said heterostructure (7) with a light flux in order to polymerize the adhesive layer (6),
- (e) heat treating the irradiated heterostructure (7),
- (f) thinning the piezoelectric substrate (5) from the side thereof opposite the handle substrate (2), so as to form said donor substrate (1).

Figure for the abstract: Figure 6